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Product Change Notification - JAON-08BVJU876 (Printer Friendly)

Date:

20 Mar 2017

Product Category:

Memory; Power MOSFET Drivers; Interface- Infrared Products; Sigma - Delta A/D Converters; Digital Potentiometers; System D/A Converters; Linear Op Amps; Linear Comparators; Instrumentation Amplifier; Linear Programmable Gain Amplifiers; Capacitive Touch Sensors; 8-bit PIC Microcontrollers; Temperature Sensors

Notification subject:

CCB 1835 Final Notice: Qualification of CuPdAu bond wire in selected products of the 40K, 42K, 77K, 120K, 150K, 160K and 200K wafer technologies available in 8L SOIC package at MMT assembly site.

Notification text:

PCN Status:

Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 40K, 42K, 77K, 120K, 150K, 160K and 200K wafer technologies available in 8L SOIC package at MMT assembly site.

Pre Change:

Gold (Au) or Palladium coated copper wire (PdCu) bond wire

Post Change:

Palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	MMT assembly site	MMT assembly site

Wire material	Au wire or PdCu wire	CuPdAu wire
Die attach material	8390A	8390A
Molding compound material	G600V	G600V
Lead frame material	CDA194	CDA194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying Palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:

In Progress

Estimated First Ship Date:

April 20, 2017 (date code: 1716)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	January 2016			- ^	March 2017			April 2017						
WW	01	02	03	04		09	10	11	12	13	14	15	16	17
Initial PCN Issue Date		Χ												
Qual Report Availability									X					
Final PCN Issue Date									Χ					
Implementation Date													Χ	

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

January 13, 2016: Issued initial notification.

March 20, 2017: Issued final notification. Attached the qualification report. Revised the estimated first ship date from April 20, 2016 to April 16, 2017. Updated subject and description to include selected products of the 40K, 42K, 77K, 120K, 150K and 160K wafer technologies.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_JAON-08BVJU876_Qual Report.pdf PCN_JAON-08BVJU876_Affected_CPN.pdf PCN_JAON-08BVJU876_Affected_CPN.xls

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